

FIG. 5

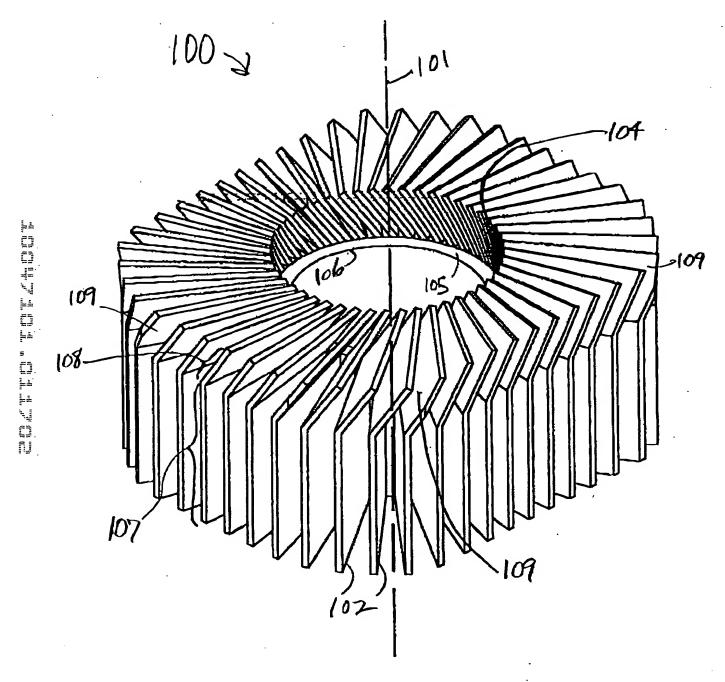
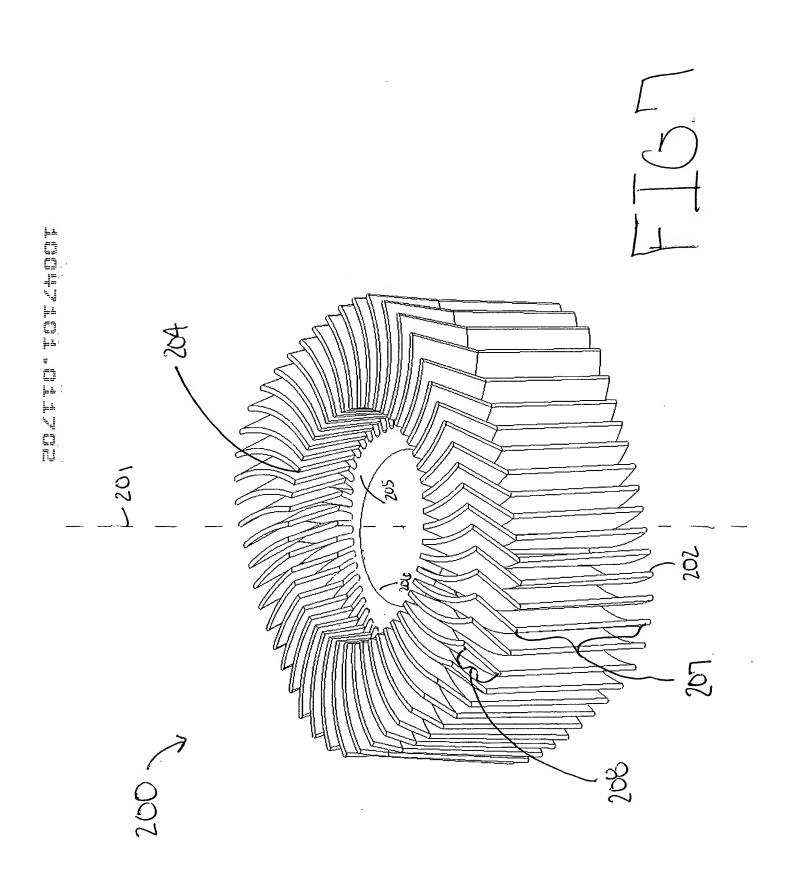
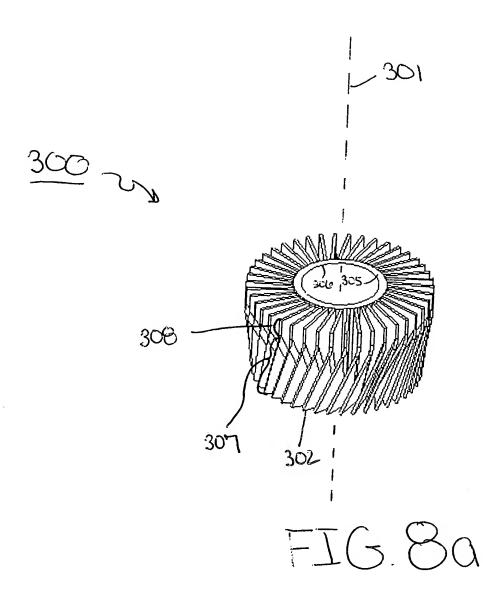


FIG. 6





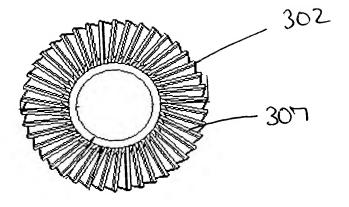
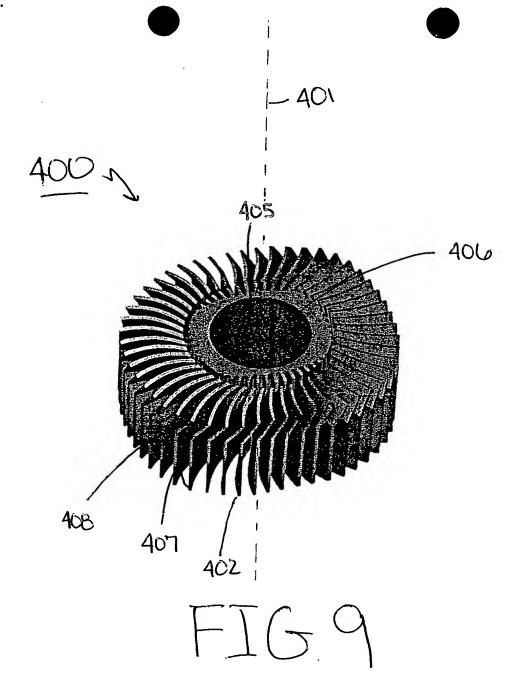
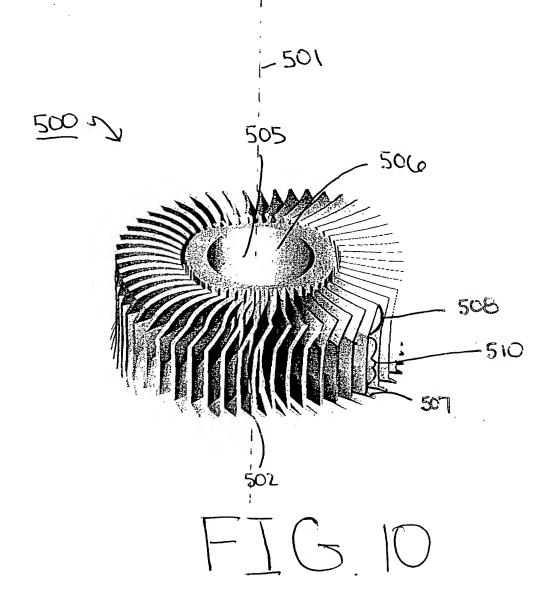


FIG.86





520 N

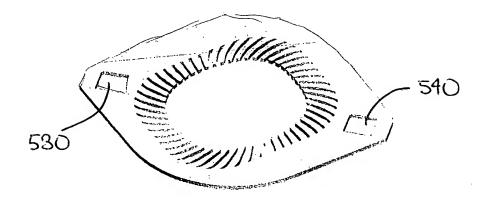


FIG. 11a

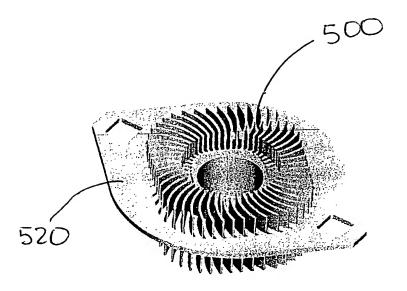
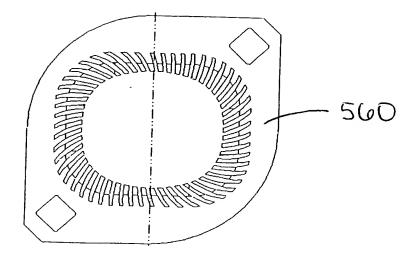
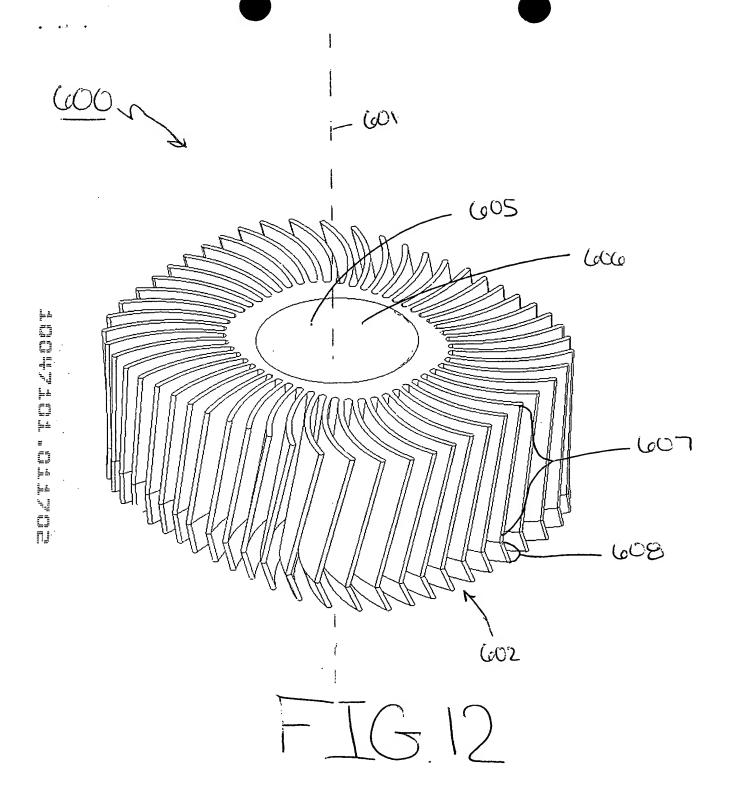


FIG.11b



FIGMO



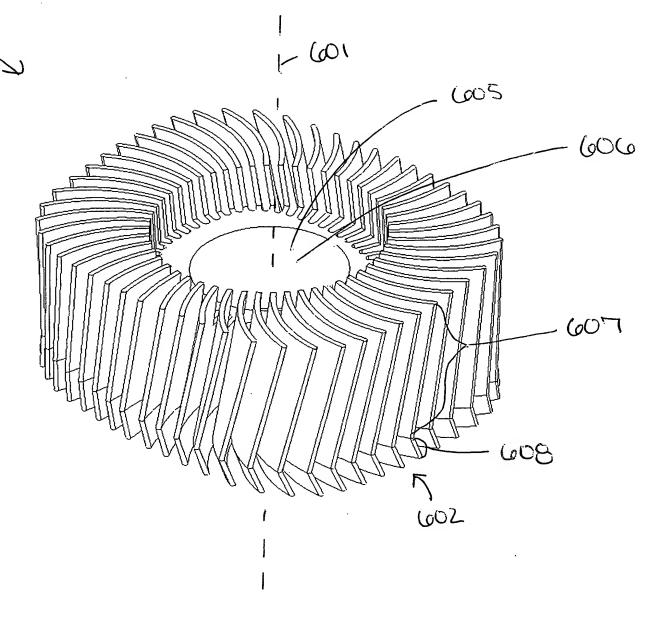


FIG 13

802 MOUNT AN ELECTRONIC COMPONENT ON A CIRCUIT BOARD SOA PROVIDE AN AXIAL FLOW FAN CAPABLE OF MOVING AIR HAVING A COMPONENT NORMAL TO THE ELECTRONIC COMPONENT AND A COMPONENT TANGENTIAL TO THE **ELECTRONIC COMPONENT** 80W-MOUNT A HEAT SINK BETWEEN THE ELECTRONIC COMPONENT AND THE FAN - THE HEAT SINK INCLUDES A NUMBER OF COOLING FINS ARRANGED ABOUT A CORE HAVING A CENTRAL AXIS - EACH COOLING FIN HAS A BASE COUPLED TO THE CORE SUBSTANTIALLY PARALLEL TO THE CENTRAL AXIS - THE COOLING FINS ARE SHAPED TO CAPTURE BOTH COMPONENTS OF AIR A FIRST FACE OF THE HEAT SINK IS IN THERMAL CONTACT WITH THE ELECTRONIC COMPONENT AND HAS A SEMI-RECTANGULAR PERIPHERY - A SECOND FACE OF THE HEAT SINK FACES THE FAN AND HAS A SEMI-RECTANGULAR PERIPHERY - THE CORE IS SHAPED TO MAXIMIZE THE NUMBER OF COOLING FINS WHILE MAINTAINING A SUBSTANTIALLY UNIFORM ASPECT RATIO IN THE COOLING FINS END

FIG 15

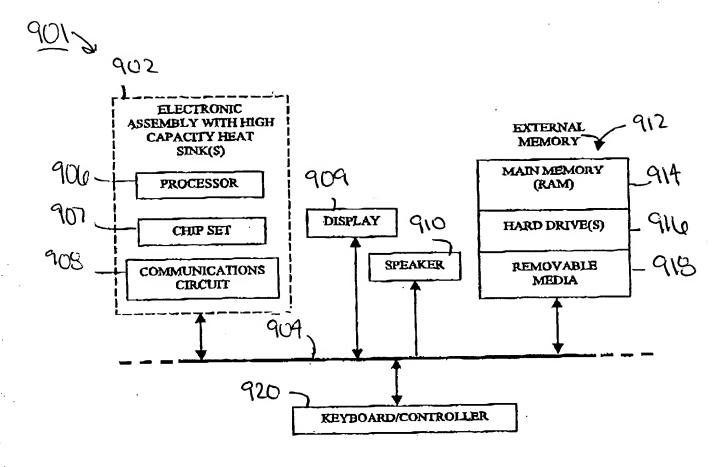


FIG. 10